

## EAST Search History

| Ref # | Hits | Search Query                        | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|-------------------------------------|---|------------------|---------|------------------|
| L1    | 274  | semiconductor and (back\$2grinding) | USPAT   | OR               | OFF     | 2006/10/05 11:59 |
| L2    | 489  | semiconductor and (back\$2grinding) | US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/10/05 11:59 |

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| Ref # | Hits  | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|-------|---|---|------------------|---------|------------------|
| L1    | 10246 | (semiconductor adj (wafer or chip or die or ic)) and (protect\$4 near4 (sheet or layer or structure)) | USPAT   | OR               | ON      | 2006/10/05 09:43 |
| L2    | 4063  | (semiconductor adj (wafer or chip or die or ic)) and (protect\$4 adj1 (sheet or layer or structure))  | USPAT   | OR               | ON      | 2006/10/05 09:45 |
| L3    | 2447  | (semiconductor adj wafer) and (protect\$4 adj1 (sheet or layer or structure))                         | USPAT   | OR               | ON      | 2006/10/05 10:44 |
| L4    | 2352  | (semiconductor adj wafer) and (protect\$4 adj1 (sheet or layer or structure))                         | US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/10/05 10:44 |